



THE UNITED STATES PATENT AND TRADEMARK OFFICE

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APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557
SERIAL NO.: 10/815,103 ART UNIT: 2826
FILED: 03/31/2004 EXAMINER: L. ANDUJAR
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE
SOLDERS AND HAVING REACTION BARRIER LAYERS
ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

Responsive to the final Office Action of October 3,
2007, please reconsider and allow this application in view
of the following:

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Remarks	Page 7

Certificate of Mailing

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deposited with the United States Postal Service as first
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January 3, 2008
Date

David Aher
Name of Person Making Deposit